SMD Multilayer Ferrite Chip Inductor

- JMF series

1-1.Mechanical Performances

No	Item	Specification	Test Method
1-1-1	Flexure Strength	The forces applied on the right conditions must not damage the terminal electrode and the ferrite.	Test device shall be soldered on the substrate Substrate Dimension: 100x40x1.6mm Deflection: 2.0mm Keeping Time: 30sec *For 100505, substrate dimension is 100x40x0.8mm
1-1-2	Vibration		Test device shall be soldered on the substrate Oscillation Frequency: 10 to 55 to 10Hz for 1min Amplitude: 1.5mm Time: 2hrs for each axis (X, Y & Z), total 6hrs
1-1-3	Resistance to Soldering Heat	Appearance: No damage More than 75% of the terminal electrode should be covered with solder. Inductance: within ±0% of initial value Q change: within ±0% of initial value	Pre-heating: 150 , 1min Solder Composition: Sn/Pb = 63/37 Solder Temperature: 260
1-1-4	Solder ability	The electrodes shall be at least 90% covered with new solder coating	Pre-heating: 150 , 1min Solder Composition: Sn/Pb = 63/37 Solder Temperature: 220 £ Immersion Time: 4 £sec

1-2.Environmental Performances

No	Item	Specification	Test Method						
1-2-1	Temperature Cycle	Appearance: No damage	On	One cycle:					
		Inductance: within ±10% of initial		Step	Temperature ()	Time (min)			
		value		1	-25 £	30			
		Q change: within £0% of initial		2	25 £	3			
		value		3	85 £	30			
				4	25 £	3			
			To	tal: 100cy					
			Me	easured at	24hrs				
1-2-2	Humidity Resistance	1		Temperature: 40 €					
			Relative Humidity: 90 ~ 95%						
			Time: 1000hrs						
		1	Measured after exposure in the room condition for 24hrs						
1-2-3	High Temperature		Temperature: 85 £						
	Resistance		Relative Humidity: 20%						
				Applied Current: Rated Current					
			Time: 1000hrs						
		4	Measured after exposure in the room condition for 24hrs						
1-2-4	Low Temperature		Temperature: -25 -8						
	Resistance		Relative Humidity: 0%						
			Time: 1000hrs						
			Me	easured at	fter exposure in the roo	m condition for	24hrs		